2-Input AND Gate with Open Drain Output

The MC74VHC1G09 is an advanced high speed CMOS 2-input AND gate with open drain output fabricated with silicon gate CMOS technology. It achieves high speed operation similar to equivalent Bipolar Schottky TTL while maintaining CMOS low power dissipation.

The internal circuit is composed of three stages, including an open drain output which provides the capability to set output switching level. This allows the MC74VHC1G09 to be used to interface 5.0 V circuits to circuits of any voltage between V_{CC} and 7.0 V using an external resistor and power supply.

The MC74VHC1G09 input structure provides protection when voltages up to 7.0 V are applied, regardless of the supply voltage.

Features

- High Speed: $t_{PD} = 4.3 \text{ ns}$ (Typ) at $V_{CC} = 5.0 \text{ V}$
- Low Internal Power Dissipation: $I_{CC} = 1 \mu A$ (Max) at $T_A = 25^{\circ}C$
- Power Down Protection Provided on Inputs
- Pin and Function Compatible with Other Standard Logic Families
- Chip Complexity: FETs = 62; Equivalent Gates = 16
- Pb-Free Packages are Available

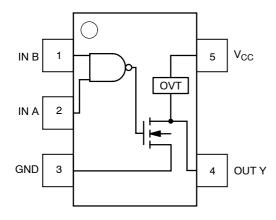


Figure 1. Pinout (Top View)

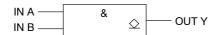


Figure 2. Logic Symbol



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MARKING DIAGRAMS



SC-88A / SOT-353 / SC-70 DF SUFFIX CASE 419A





TSOP-5 / SOT-23 / SC-59 DT SUFFIX CASE 483



M = Date Code

A = Assembly Location

Y = Year

V = Work Week

■ = Pb-Free Package

(Note: Microdot may be in either location)

PIN ASSIGNMENT					
1	IN B				
2	IN A				
3	GND				
4	OUT Y				
5	V _{CC}				

FUNCTION TABLE

Inp	uts	Output
Α	В	Υ
L	L	L
L	Н	L
Н	L	L
Н	Н	Z

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MAXIMUM RATINGS

Symbol	Chara	ncteristics	Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to +7.0	V
V _{IN}	DC Input Voltage		-0.5 to +7.0	V
V _{OUT}	DC Output Voltage		-0.5 to 7.0	V
I _{IK}	Input Diode Current		-20	mA
I _{OK}	Output Diode Current		+20	mA
l _{out}	DC Output Current, per Pin		+25	mA
I _{CC}	DC Supply Current, V _{CC} and GND		+50	mA
P_{D}	Power dissipation in still air	SC-88A, TSOP-5	200	mW
θ_{JA}	Thermal resistance	SC-88A, TSOP-5	333	°C/W
T _L	Lead temperature, 1 mm from case for 1	0 s	260	°C
T_J	Junction temperature under bias		+150	°C
T _{stg}	Storage temperature		-65 to +150	°C
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V _{ESD}	ESD Withstand Voltage	Human Body Model (Note 1) Machine Model (Note 2) Charged Device Model (Note 3)	> 2000 > 200 N/A	V
I _{Latchup}	Latchup Performance Abov	ve V _{CC} and Below GND at 125°C (Note 4)	±500	mA

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

- 1. Tested to EIA/JESD22-A114-A
- 2. Tested to EIA/JESD22-A115-A
- 3. Tested to JESD22-C101-A
- 4. Tested to EIA/JESD78

RECOMMENDED OPERATING CONDITIONS

Symbol	Characteristics			Max	Unit
V _{CC}	DC Supply Voltage		2.0	5.5	V
V _{IN}	DC Input Voltage		0.0	5.5	V
V _{OUT}	DC Output Voltage		0.0	7.0	V
T _A	Operating Temperature Range		-55	+125	°C
t _r , t _f	Input Rise and Fall Time V _C	$C = 3.3 \text{ V} \pm 0.3 \text{ V}$ $C = 5.0 \text{ V} \pm 0.5 \text{ V}$	0 0	100 20	ns/V

Device Junction Temperature versus Time to 0.1% Bond Failures

Junction Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

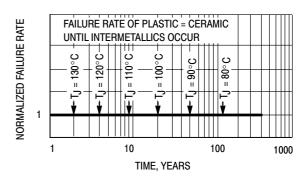


Figure 3. Failure Rate vs. Time **Junction Temperature**

DC ELECTRICAL CHARACTERISTICS

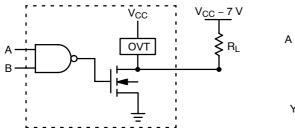
			v _{cc}	1	Γ _A = 25°()	T _A ≤	85°C	-55 ≤ T _A	≤ 125°C	
Symbol	Parameter	Test Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V _{IH}	Minimum High-Level Input Voltage		2.0 3.0 4.5 5.5	1.5 2.1 3.15 3.85			1.5 2.1 3.15 3.85		1.5 2.1 3.15 3.85		V
V _{IL}	Maximum Low-Level Input Voltage		2.0 3.0 4.5 5.5			0.5 0.9 1.35 1.65		0.5 0.9 1.35 1.65		0.5 0.9 1.35 1.65	V
V _{OL}	Maximum Low-Level Output Voltage V _{IN} = V _{IH} or V _{IL}	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 50 \mu\text{A}$	2.0 3.0 4.5		0.0 0.0 0.0	0.1 0.1 0.1		0.1 0.1 0.1		0.1 0.1 0.1	V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 4 \text{ mA}$ $I_{OL} = 8 \text{ mA}$	3.0 4.5			0.36 0.36		0.44 0.44		0.52 0.52	٧
I _{IN}	Maximum Input Leakage Current	V _{IN} = 5.5 V or GND	0 to 5.5			±0.1		±1.0		±1.0	μΑ
Icc	Maximum Quiescent Supply Current	V _{IN} = V _{CC} or GND	5.5			1.0		20		40	μΑ
l _{OFF}	Power Off-Output Leakage Current	V _{OUT} = 5.5 V V _{IN} = 5.5 V	0			0.25		2.5		5	μΑ

AC ELECTRICAL CHARACTERISTICS C_{load} = 50 pF, Input t_{r} = t_{f} = 3.0 ns

			7	T _A = 25°C		T _A ≤	85°C	-55 ≤ T _A	≤ 125°C	
Symbol	Parameter	Test Conditions	Min	Тур	Max	Min	Max	Min	Max	Unit
t _{PZL}	Maximum Output Enable Time, Input A or B to Y	$\begin{array}{c} V_{CC} = 3.3 \pm 0.3 \; V \; C_L = 15 \; pF \\ R_L = R_I = 500 \; \Omega C_L = 50 \; pF \end{array}$		6.2 8.7	8.8 12.3		10.5 14.0		12.5 16.5	ns
	input A or B to 1	$\begin{tabular}{lllllllllllllllllllllllllllllllllll$		4.3 5.8	5.9 7.9		7.0 9.0		9.0 11.0	
t _{PLZ}	Maximum Output Disable Time	$\begin{aligned} &V_{CC} = 3.3 \pm 0.3 \text{ V C}_{L} = 50 \text{ pF} \\ &R_{L} = R_{I} = 500 \Omega \end{aligned}$		8.7	12.3		14.0		16.5	ns
		$V_{CC} = 5.0 \pm 0.5 \text{ V C}_{L} = 50 \text{ pF}$ $R_{L} = R_{I} = 500 \Omega$		5.8	7.9		9.0		11.0	
C _{IN}	Maximum Input Capacitance			6.0	10		10		10	pF

		Typical @ 25°C, V _{CC} = 5.0 V	
C _{PD}	Power Dissipation Capacitance (Note 5)	18	pF

^{5.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no–load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.



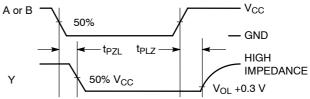
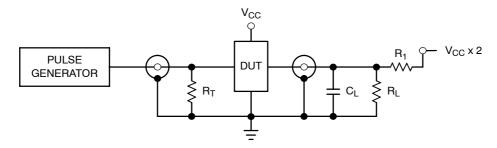


Figure 4. Output Voltage Mismatch Application

Figure 5. Switching Waveforms

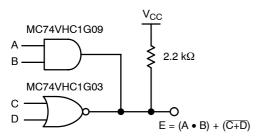


 C_L = 50 pF equivalent (Includes jig and probe capacitance)

 R_L = R_1 = 500 Ω or equivalent

 $R_T = Z_{OUT}$ of pulse generator (typically 50 Ω)

Figure 6. Test Circuit



B 1 5 RLED

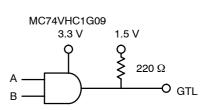


Figure 7. Complex Boolean Functions

Figure 8. LED Driver

Figure 9. GTL Driver

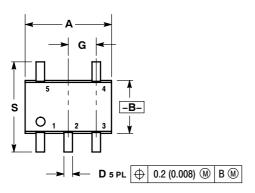
DEVICE ORDERING INFORMATION

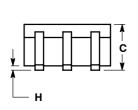
Device Order Number	Package Type	Tape and Reel Size [†]
MC74VHC1G09DFT1	SC70-5 / SC-88A / SOT-353	178 mm (7") 3000 Unit
MC74VHC1G09DFT1G	SC70-5 / SC-88A / SOT-353 (Pb-Free)	178 mm (7") 3000 Unit
MC74VHC1G09DFT2	SC70-5 / SC-88A / SOT-353	178 mm (7") 3000 Unit
MC74VHC1G09DFT2G	SC70-5 / SC-88A / SOT-353 (Pb-Free)	178 mm (7") 3000 Unit
MC74VHC1G09DTT1	SOT23-5 / TSSOP-5 / SC59-5	178 mm (7") 3000 Unit
MC74VHC1G09DTT1G	SOT23-5 / TSSOP-5 / SC59-5 (Pb-Free)	178 mm (7") 3000 Unit

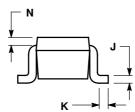
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

SC-88A, SOT-353, SC-70 CASE 419A-02 **ISSUE J**







- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

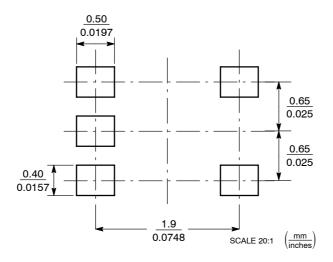
 2. CONTROLLING DIMENSION: INCH.

 3. 419A-01 OBSOLETE. NEW STANDARD 419A-02.

 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	INC	HES	MILLIN	IETERS
DIM	MIN	MIN MAX		MAX
Α	0.071	0.087	1.80	2.20
В	0.045	0.053	1.15	1.35
C	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026	BSC	0.65	BSC
Н		0.004		0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008	REF	0.20	REF
S	0.079	0.087	2.00	2.20

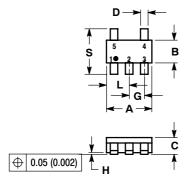
SOLDERING FOOTPRINT*

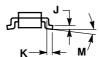


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSOP-5/SOT-23/SC-59 CASE 483-02 ISSUE D



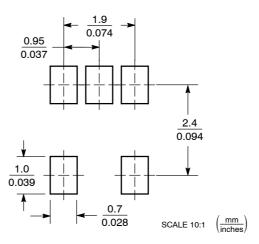


NOTES

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- A AND B DIMENSIONS DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	2.90	3.10	0.1142	0.1220
В	1.30	1.70	0.0512	0.0669
С	0.90	1.10	0.0354	0.0433
D	0.25	0.50	0.0098	0.0197
G	0.85	1.05	0.0335	0.0413
Н	0.013	0.100	0.0005	0.0040
J	0.10	0.26	0.0040	0.0102
K	0.20	0.60	0.0079	0.0236
L	1.25	1.55	0.0493	0.0610
М	0 °	10°	0°	10°
S	2.50	3.00	0.0985	0.1181

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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